

### TK39N60X-VB Datasheet

# N-Channel 600V (D-S) Super Junction Power MOSFET

PRODUCT SUMMA	RY	
V <sub>DS</sub> (V) at T <sub>J</sub> max.	600	)
R <sub>DS(on)</sub> at 25 °C (Ω)	V <sub>GS</sub> = 10 V	0.060

#### **FEATURES**

- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Qg)
- Avalanche energy rated (UIS)

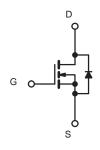
#### **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- - High-intensity discharge (HID)
  - Fluorescent ballast lighting









N-Channel MOSFET

Top View

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)							
PARAMETER			SYMBOL	LIMIT	UNIT		
Drain-Source Voltage			$V_{DS}$	600	V		
Gate-Source Voltage			$V_{GS}$	± 30	7 v		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	$T_{\rm C} = 25  ^{\circ}{\rm C}$ $T_{\rm C} = 100  ^{\circ}{\rm C}$	I <sub>D</sub>	47			
	VGS at 10 V	T <sub>C</sub> = 100 °C		29	A		
Pulsed Drain Current <sup>a</sup>			I <sub>DM</sub>	140			
Linear Derating Factor				1.67	W/°C		
Single Pulse Avalanche Energy b			E <sub>AS</sub>	850	mJ		
Maximum Power Dissipation			$P_{D}$	510	W		
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C		
Drain-Source Voltage Slope	T <sub>J</sub> = 125 °C		d\//dt	50	1//20		
Reverse Diode dV/dt d	•		dV/dt	15	- V/ns		
Soldering Recommendations (Peak Temperature) c	for	10 s		260	°C		

- a. Repetitive rating; pulse width limited by maximum junction temperature. b.  $V_{DD}=100$  V, starting  $T_J=25$  °C, L = 30mH,  $R_g=25$   $\Omega$ ,  $I_{AS}=24$ A.
- c. 1.6 mm from case.
- d.  $I_{SD} \le I_D$ , dI/dt = 100 A/ $\mu$ s, starting  $T_J = 25$  °C.



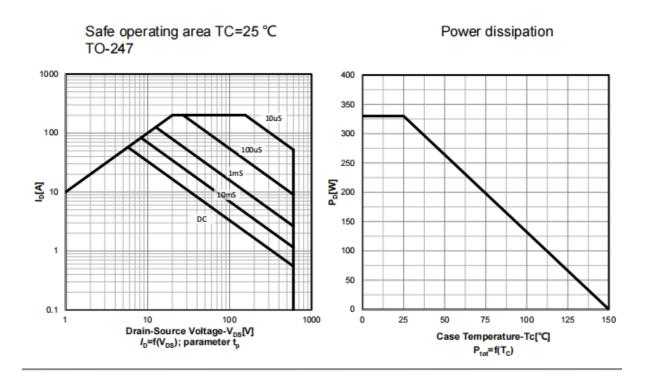
THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	62	°C/W
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	-	0.38	G/ VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		-					•
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> :	= 0 V, I <sub>D</sub> = 1 mA	600	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I <sub>D</sub> = 1 mA	-	0.70	-	V/°C
Gate-Source Threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2.5	-	4.5	V
			V <sub>GS</sub> = ± 20 V	-	-	± 100	nA
Gate-Source Leakage	$I_{GSS}$		V <sub>GS</sub> = ± 30 V	_	-	± 1	μΑ
			= 600V, V <sub>GS</sub> = 0 V	_	-	1	<del>_</del>
Zero Gate Voltage Drain Current	I <sub>DSS</sub>		$V_{DS} = 600V, V_{GS} = 0 V$ $V_{DS} = 480 V, V_{GS} = 0 V, T_{J} = 125 °C$		-	100	μA
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> =16A	-	0.060	-	Ω
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub>	s = 30 V, I <sub>D</sub> = 16 A	-	5.6	-	S
Dynamic		•					
Input Capacitance	C <sub>iss</sub>		V <sub>GS</sub> = 0 V,	-	4900	-	
Output Capacitance	Coss	V <sub>DS</sub> = 100 V, f = 1 MHz		-	330	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>			-	4	-	
Effective Output Capacitance, Energy Related <sup>a</sup>	C <sub>o(er)</sub>	- V <sub>DS</sub> = 0 V to 520 V, V <sub>GS</sub> = 0 V		-	63	-	
Effective Output Capacitance, Time Related <sup>b</sup>	C <sub>o(tr)</sub>			-	213	-	
Total Gate Charge	Qg			_	370	-	
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$I_D = 20 \text{ A}, V_{DS} = 520 \text{ V}$	-	3 9	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	1		-	4 7	-	
Turn-On Delay Time	t <sub>d(on)</sub>			-	18	25	
Rise Time	t <sub>r</sub>	V <sub>DD</sub> = 520 V, I <sub>D</sub> = 20A,		-	24	55	ns
Turn-Off Delay Time	t <sub>d(off)</sub>			-	8 0	-	
Fall Time	t <sub>f</sub>	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		-	1 2	-	
Gate Input Resistance	$R_g$	f = 1 MHz, open drain		-	8.0	-	Ω
<b>Drain-Source Body Diode Characteristic</b>	s						
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	47	_
Pulsed Diode Forward Current	I <sub>SM</sub>			-	-	140	A
Diode Forward Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 8 A, V <sub>GS</sub> = 0 V		-	-	1.5	V
Reverse Recovery Time	t <sub>rr</sub>			-	520	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = I <sub>S</sub> = 8 A, dl/dt = 100 A/µs, V <sub>R</sub> = 400 V		-	5.8	-	μC
Reverse Recovery Current	I <sub>RRM</sub>				4 5	_	A

#### Notes

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ . b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .





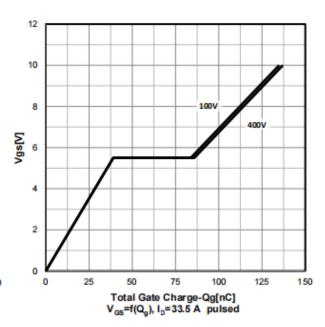
Typ. output characteristics  $T_i$ =25  $^{\circ}$ C Transfer characteristics 300 300 25°C . I<sub>D</sub>, Drain Current [A] Drain Current [A] 200 150°C -0 5 10 0 15 20 0 2 10 12 V<sub>GS</sub>, Gate-Source Voltage [V] V<sub>DS</sub>, Drain to Source Voltage [V]



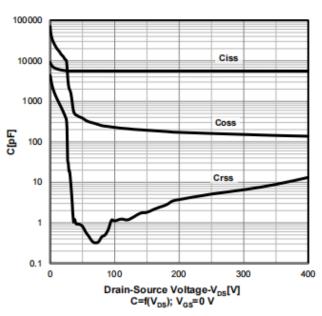
Typ. drain-source on-state resistance

80
70
60
60
40
30
20
0 15 30 45 60 75 90
Drain-Source Current-I<sub>D</sub>[A]
R<sub>DS</sub>(on)=f(I<sub>D</sub>); parameter: V<sub>GS</sub>

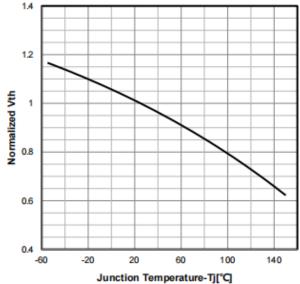
Typ. gate charge characteristics



Typ. capacitances

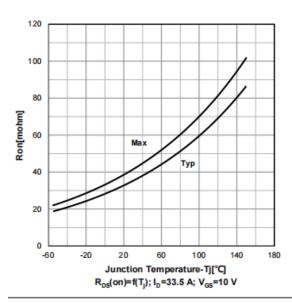


## Normalized $V_{\text{GS(th)}}$ characteristics

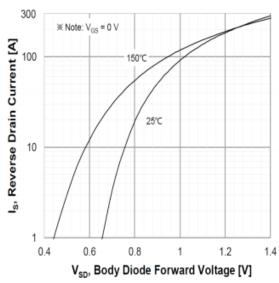




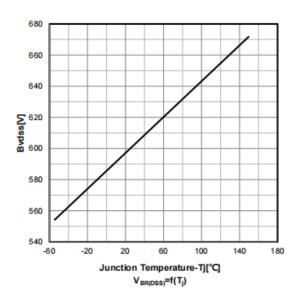
#### On-resistance vs temperature



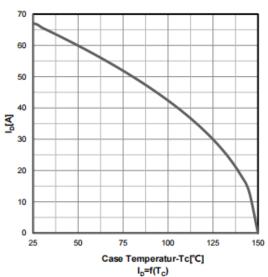
#### Forward characteristics of reverse diode



#### Drain-source breakdown voltage



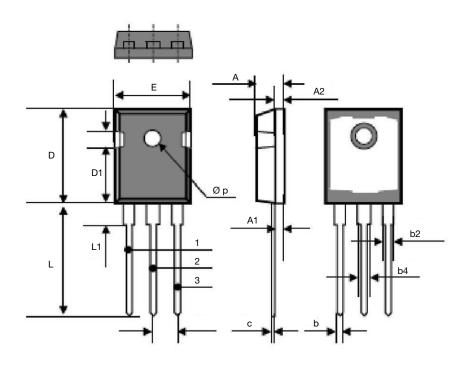
#### Drain current vs temperature



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TO-247



DIM.	MILLIN	METERS	INCHES		
	MIN.	MAX.	MIN.	MAX.	
Α	4.70	5.31	0.185	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.50	2.49	0.059	0.098	
b	0.99	1.40	0.039	0.055	
b2	1.65	2.41	0.065	0.095	
b4	2.59	3.43	0.102	0.135	
С	0.61 BSC		0.024 BSC		
D	20.80	21.46	0.819	0.845	
D1	3.68	5.49	0.145	0.216	
(e)	5.46 BSC		0.215 BSC		
E	15.49	16.26	0.610	0.640	
L	19.81	20.32	0.780	0.800	
L1	4.06	4.50	0.160	0.177	
Øр	3.51	3.66	0.138	0.144	



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